

Precautions

1. The chip is stored in a dry, nitrogen environment and used in an ultra-clean environment; 2. GaAs material is relatively brittle and cannot touch the surface of the chip, so you must be careful when using it;
3. The chip is sintered with conductive glue or alloy (the alloy temperature cannot exceed 300°C, and the time cannot exceed 30 seconds), so that it is fully grounded; 4. 4. The gap between the microwave port of the chip and the substrate should not exceed 0.05mm. Use $\Phi 25\mu\text{m}$ double gold wire for bonding. The recommended length of gold wire is 250~400 μm ; The chip is sensitive to static electricity, so pay attention to anti-static during storage and use.